## nexperia

## **Quarterly Reliability Monitoring Results**

Quarters: Q3/2021 to Q4/2022

Based on structural similarity

| Supplier<br>Nexperia B.V.<br>Name of Laboratory<br>Assembly reliability labs<br>Based on AEC-Q101 Test |  | User Part Number  |                                   |           |            |           |  |                          |
|--|--|---|-----------------------------------|-----------|------------|-----------|--|--------------------------|
|  |  | PESD3V3F2UT Part Description  |                                   |           |            |           |  |                          |
|  |  |   |                                   |           |            |           |  | NXP ICN8 Protection INDI |
|  |  | SMD package   |                                   |           |            |           |  |                          |
|  |  | Test Conditions   | Duration                          | # Lots    | # Quantity | # Rejects |  |                          |
|  |  |   | TEST                              |           |            |           |  |                          |
|  | Pre- and Post-Stress   |   |                                   |           |            |           |  |                          |
| # E1   | Electrical Test  | Tamb = 25 °C  | N/A                               | see below | all parts  | see below |  |                          |
| # A1   | <b>PC</b><br>Preconditioning                                   | JESD22-A113<br>Bake Tamb = 125 °C<br>Soak Tamb = 85 °C, RH = 85%<br>Reflow soldering                | 24 hours<br>168 hours<br>3 cycles | 438       | 24630      | 0         |  |                          |
| # B1   | HTRB<br>High Temperature Reverse<br>Bias                       | MIL-STD-750-1<br>M1038 Method A<br>Tj = Tjmax, Vr = 100% of max. datasheet<br>reverse voltage       | 1000 hours                        | 21        | 1280       | 0         |  |                          |
| # A4   | <b>TC</b><br>Temperature Cycling                               | JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C   | 1000 cycles                       | 131       | 7760       | 0         |  |                          |
| # A3 <b>or</b>   | <b>UHAST</b><br>Unbiased HAST                                  | JESD22-A118<br>Tamb = 130 °C, RH = 85 %   | 96 hours                          | 131       | 7760       | 0         |  |                          |
| # A3 alt   | <b>AC</b><br>Autoclave   | JESD22-A102<br>Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia)                          |                                   |           |            |           |  |                          |
| # A2 alt   | <b>H3TRB</b><br>High Humidity High<br>Temperature Reverse Bias | JESD22-A101<br>Tamb = 85 °C, RH = 85%, VR = 80 % of<br>rated reverse voltage <sup>[1]</sup>         | 1000 hours                        | 131       | 7760       | 0         |  |                          |
| # A5   | <b>IOL</b><br>Intermittent Operating Life                      | MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj$ = 100 °C for 15000 cycles | 1000 hours                        | n.a.      | n.a.       | n.a.      |  |                          |
| # C8   | <b>RSH</b><br>Resistance to Solder Heat                        | JESD22-A111<br>260 °C ± 5 °C  | 10 s                              | 45        | 1350       | 0         |  |                          |
| # C10  | <b>SD</b><br>Solderability                                     | J-STD-002   |                                   | 111       | 1110       | 0         |  |                          |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology      | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|-----------------|----------|---------|--------------------|------------|
| NXP ICN8  | Protection INDI | 1280     | 0       | 3,32               | 3,01E+08   |

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